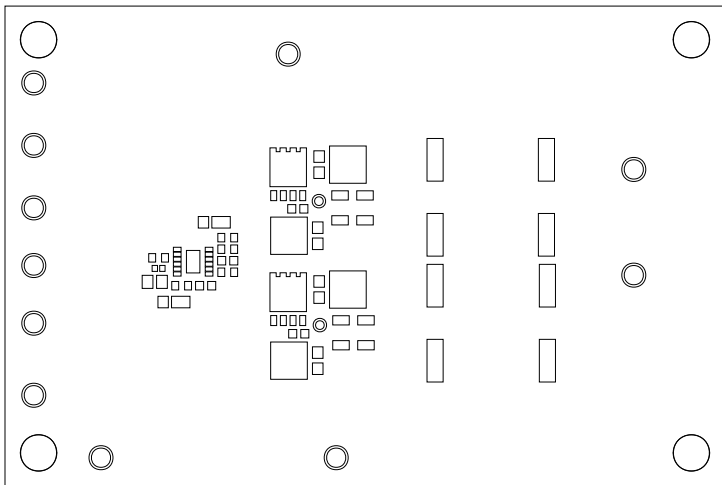
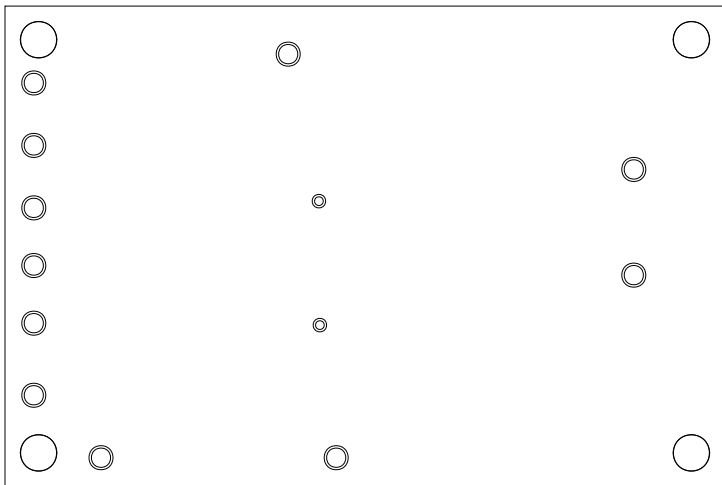


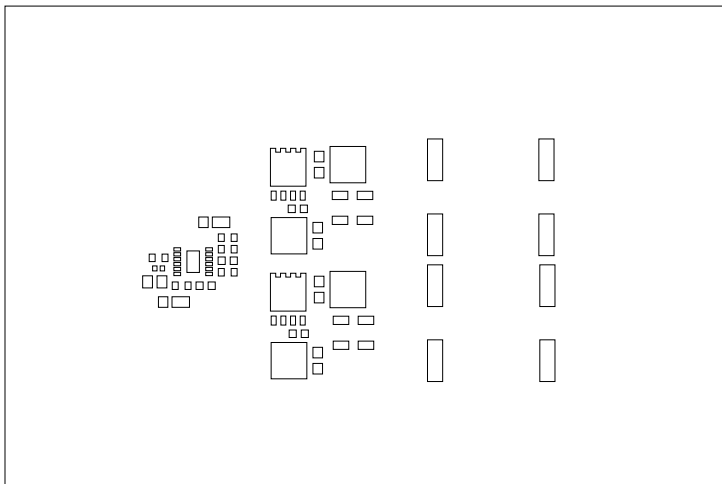
L1 PRIMARY  
08-072118 -01      DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B



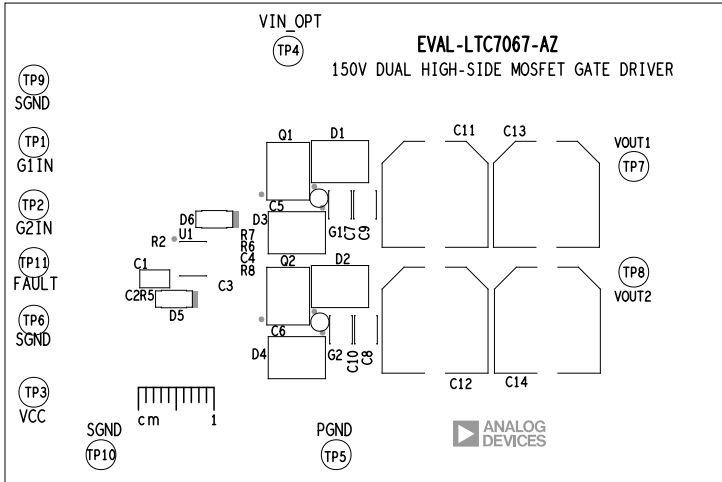
SOLDERMASK PRIMARY  
08-072118 -04      DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B



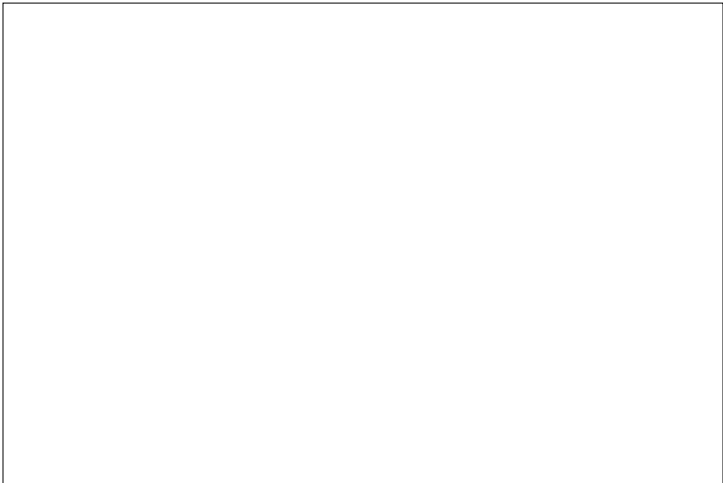
SOLDERMASK SECONDARY  
08-072118 -06      DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B



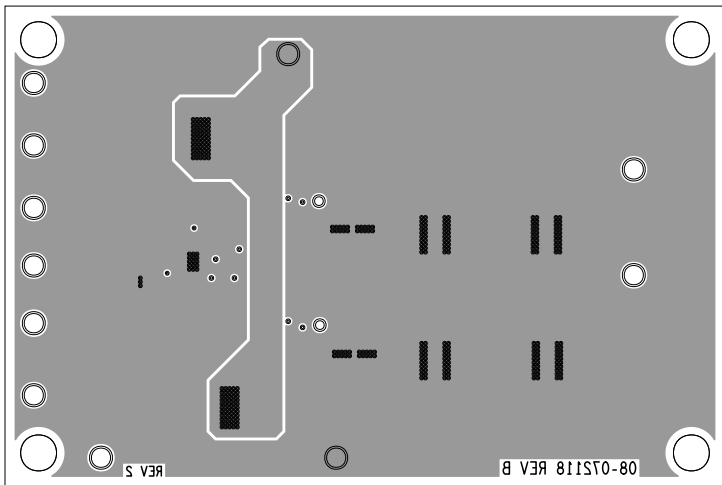
PASTEMASK PRIMARY  
08-072118-13      DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B



SILKSCREEN PRIMARY  
08-072118 -03 DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B

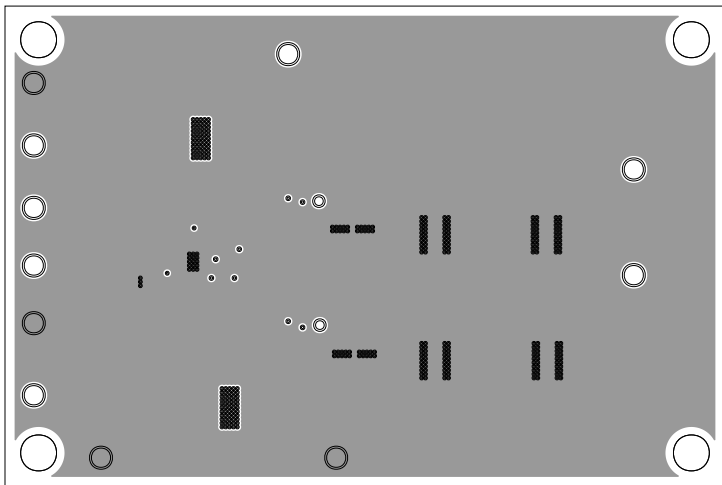


SILKSCREEN SECONDARY  
08-072118 -05      DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B

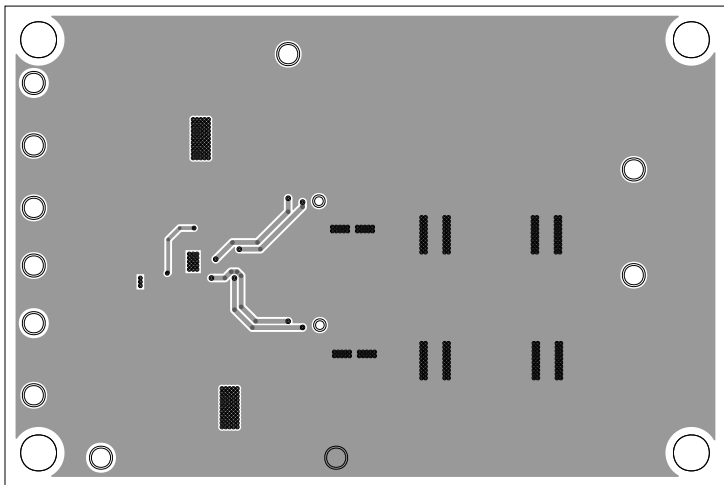


L4 SECONDARY  
08-072118 -10      DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B





L2  
08-072118 -08      DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B



L3  
08-072118 -09      DATE: 2-1-2023  
EVAL-LTC7067-AZ REV B

87654321

REVISIONS

REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	10-03-2022	X
B	ECR-112470	1-17-2023	X

4 LAYER STACKUP

NOMINAL  
FINISHED  
THICKNESS  
0.062" +/-10%

PRIMARY SILKSCREEN

PRIMARY SOLDER MASK

PRIMARY SIDE (LAYER 1)

0.0035" INNER LAYER (LAYER 2)

INNER LAYER (LAYER 3)

0.0035" SECONDARY SIDE (LAYER 4)

SECONDARY SOLDER MASK

SECONDARY SILKSCREEN

SPECIFICATIONS:

MATERIALS;

MATERIAL FAMILY;

CLADDING;

SOLDER MASK;

SILK SCREEN;

SURFACE FINISH;

INTENTIONAL SHORTS;

TEST REQUIREMENTS;

ALL LAMINATES AND BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103, MINIMUM Tg>170degC, Td>300degC, U.L. RATING OF 94 V-0

FR4

EXTERNAL LAYERS 2 OZ. COPPER.  
INTERNAL LAYERS 1 OZ. COPPER.

NOTE: IF THE LAYER STACKUP CONFLICTS WITH THE ABOVE CLADDING SPECIFICATIONS THEN THE LAYER STACKUP SHALL TAKE PRECEDENCE.

SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3. COLOR BLUE.

SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK. COLOR: WHITE  
SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS.  
COLOR: WHITE

ENIG (Electroless Nickel/Immersion Gold)  
PER IPC-4552 LATEST REVISION

IF SUPPLIED DATA INCLUDES A FILE "READ\_ME.2", THEN INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT DOES NOT MATCH "READ\_ME.2" FILE PROVIDED.

100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN "GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO REQUIRED FOR "ODB++" DATA PER EMBEDDED NETLIST.

REQUIREMENTS:

1. REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.

2. ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115, (LATEST REVISION.)

3. MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.

4. HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.

5. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.

6. HOLE DIAMETERS APPLY AFTER PLATING.

7. FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.

8. MINIMUM DESIGN LINE WIDTH IS .XXX INCH.

9. MINIMUM DESIGN SPACING IS .XXX INCH.

10. NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.

11. IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFR. MAY REQUEST APPROVAL TO TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)

12. THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:

A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURES TO BE 0.200 INCH MINIMUM.

B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.

13. MFR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;

A. U.L. CODE-FLAMMABILITY RATING

D. MFR LOGO

B. DATE CODE (STAMP).

E. SUCCESSFUL ELECTRICAL TEST.

C. LOT NUMBER

14. REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED. REPAIRS ARE NOT ALLOWED IN ANY AREA DEFINED ON GOLD\_PRM AND/OR GOLD\_SEC ARTWORK LAYERS WHEN PROVIDED IN GERBER OR ODB++ DATA.

HOLE TOLERANCE

UNLESS SPECIFIED  
PLATED: +/- .003  
NON PLATED: +.002 / -.001

FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
+	10.0	PLATED	1469	
□	12.0	PLATED	8	
°	45.0	PLATED	2	
○	100.0	PLATED	11	
⬡	187.0	NON-PLATED	4	

2.500

3.750

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED  
DIMENSIONS ARE IN INCHES

TOLERANCES

DECIMALS FRACTIONS ANGLES

.XX +/- .010 --1/32 --.2

.XXX +/- .005

.XXXX +/- .0050

APPROVAL

DATE

01SEP20

01SEP20

01SEP20

01SEP20

TEMPLATE ENGINEER  
BILLY PHILLIPS

HARDWARE SERVICES  
BOB McDONALD

HARDWARE SYSTEMS  
DAVE WILLIAMS

CONCURRENT ENGINEER  
ADST LIBRARY

HARDWARE RELEASE

0909yy

FINISH

PCB DESIGNER

PTD ENGINEER

CHECKER

0909yy

0909yy

0909yy

DO NOT SCALE DWG

SCALE

1/1

SHEET

1 OF 1

TITLE

FABRICATION  
EVAL-LTC7076-AZ

SIZE

FSCM NO

DRAWING NUMBER

REV

D

24355

09-072118

B